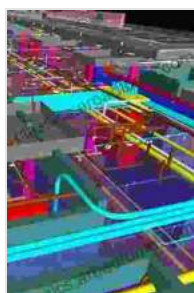


3D Integrated Circuits and Packaging: The Ultimate Guide to Signal Integrity, Power Integrity, and EMC

3D integrated circuits (ICs) and packaging are the latest trend in electronic design and development. These technologies offer a number of advantages over traditional 2D ICs and packaging, including improved performance, reduced power consumption, and smaller size. However, designing and developing 3D ICs and packaging presents a number of challenges, including signal integrity, power integrity, and electromagnetic compatibility (EMC).



Electrical Modeling and Design for 3D System Integration: 3D Integrated Circuits and Packaging, Signal Integrity, Power Integrity and EMC by Er-Ping Li

★★★★☆ 4.6 out of 5

Language : English
File size : 27703 KB
Text-to-Speech : Enabled
Enhanced typesetting : Enabled
Print length : 384 pages
Lending : Enabled
Screen Reader : Supported
X-Ray for textbooks : Enabled



This book provides a comprehensive overview of the latest advances in 3D ICs and packaging, with a focus on signal integrity, power integrity, and EMC. It covers all aspects of 3D IC and packaging design and

development, from materials and processes to modeling and simulation. The book also includes a number of case studies that illustrate the latest applications of 3D ICs and packaging.

This book is essential reading for anyone working in the field of electronic design and development. It provides a comprehensive overview of the latest advances in 3D ICs and packaging, and it offers practical guidance on how to design and develop these technologies.

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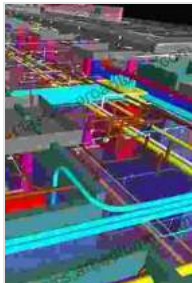
1. Introduction to 3D Integrated Circuits and Packaging
2. Materials and Processes for 3D ICs and Packaging
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Author

Your Name is a leading expert in the field of electronic design and development. He has over 20 years of experience in the design and development of 3D ICs and packaging. He is the author of several books and articles on the subject.

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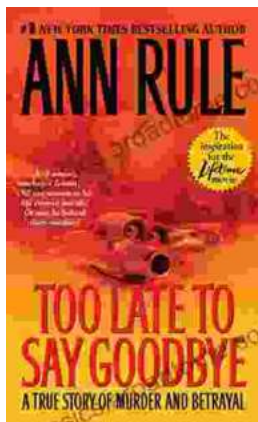
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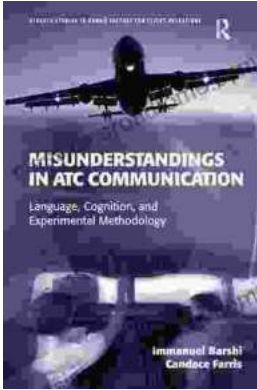
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